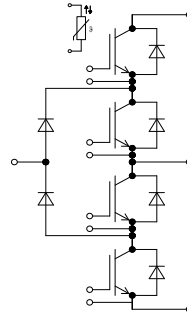
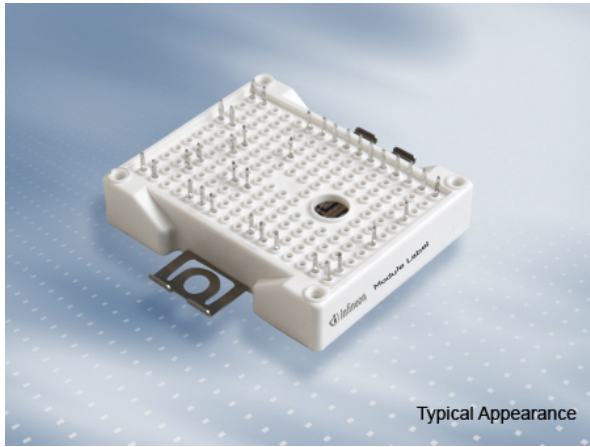


EasyPACK™ 模块 采用 TRENCHSTOP™ 5 和 CoolSiC™ 二极管 带有pressfit预涂导热材料
 EasyPACK™ module with TRENCHSTOP™ 5 and CoolSiC™ Schottky diode and PressFIT / pre-applied Thermal Interface Material



$V_{CES} = 650V$
 $I_{C\ nom} = 100A / I_{CRM} = 200A$

潜在应用

- UPS系统
- 三电平应用
- 太阳能应用
- 电机传动

Potential Applications

- UPS systems
- 3-level-applications
- Solar applications
- Motor drives

电气特性

- CoolSiC™ 碳化硅肖特基二极管第5代
- 低开关损耗
- 增加阻断电压至650V

Electrical Features

- CoolSiC™ Schottky diode gen 5
- Low switching losses
- Increased blocking voltage capability up to 650V

机械特性

- PressFIT 压接技术
- 低热阻的三氧化二铝 Al_2O_3 衬底
- 紧凑型设计
- 集成的安装夹使安装坚固
- 预涂导热介质

Mechanical Features

- PressFIT contact technology
- Al_2O_3 substrate with low thermal resistance
- Compact design
- Rugged mounting due to integrated mounting clamps
- Pre-applied Thermal Interface Material

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

Content of the Code	Digit
Module Serial Number	1 - 5
Module Material Number	6 - 11
Production Order Number	12 - 19
Datecode (Production Year)	20 - 21
Datecode (Production Week)	22 - 23

IGBT, T1 / T4 / IGBT, T1 / T4

最大额定值 / Maximum Rated Values

集电极 - 发射极电压 Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	650	V
集电极电流 Implemented collector current		I_{CN}	200	A
连续集电极直流电流 Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	110	A
集电极重复峰值电流 Repetitive peak collector current	$t_p = 1\text{ ms}$	I_{CRM}	400	A
栅极 - 发射极峰值电压 Gate-emitter peak voltage		V_{GES}	+/-20	V

特征值 / Characteristic Values

				min.	typ.	max.	
集电极 - 发射极饱和电压 Collector-emitter saturation voltage	$I_C = 100\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$		1,17 1,20 1,21	1,38	V V V
栅极阈值电压 Gate threshold voltage	$I_C = 2,40\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	3,25	4,00	4,75	V
栅极电荷 Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 400\text{ V}$		Q_G		0,84		μC
内部栅极电阻 Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$		0,0		Ω
输入电容 Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}		14,3		nF
反向传输电容 Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}		0,05		nF
集电极-发射极截止电流 Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}			1,0	mA
栅极-发射极漏电流 Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}			100	nA
开通延迟时间(电感负载) Turn-on delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{on}} = 5,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$		0,0269 0,0272 0,0276		μs μs μs
上升时间(电感负载) Rise time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{on}} = 5,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r		0,0114 0,0182 0,0194		μs μs μs
关断延迟时间(电感负载) Turn-off delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{off}} = 39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$		0,63 0,67 0,70		μs μs μs
下降时间(电感负载) Fall time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{G\text{off}} = 39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f		0,03 0,032 0,034		μs μs μs
开通损耗能量(每脉冲) Turn-on energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 5500\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{G\text{on}} = 5,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}		1,20 1,75 1,77		mJ mJ mJ
关断损耗能量(每脉冲) Turn-off energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 3500\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{G\text{off}} = 39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}		1,16 1,51 1,68		mJ mJ mJ
短路数据 SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{max}} = V_{CES} - L_{SCE} \cdot di/dt$	$t_p \leq 0\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}		1600		A
结 - 散热器热阻 Thermal resistance, junction to heatsink	每个 IGBT / per IGBT		$R_{th\text{JH}}$			0,655	K/W
在开关状态下温度 Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

IGBT, T2 / T3 / IGBT, T2 / T3

最大额定值 / Maximum Rated Values

集电极 - 发射极电压 Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{CES}	650	V
集电极电流 Implemented collector current		I_{CN}	200	A
连续集电极直流电流 Continuous DC collector current	$T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$	I_{CDC}	110	A
集电极重复峰值电流 Repetitive peak collector current	$t_p = 1\text{ ms}$	I_{CRM}	400	A
栅极 - 发射极峰值电压 Gate-emitter peak voltage		V_{GES}	+/-20	V

特征值 / Characteristic Values

				min.	typ.	max.	
集电极 - 发射极饱和电压 Collector-emitter saturation voltage	$I_C = 100\text{ A}$ $V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$		1,17 1,20 1,21	1,38	V V V
栅极阈值电压 Gate threshold voltage	$I_C = 2,40\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$		$V_{G\text{Eth}}$	3,25	4,00	4,75	V
栅极电荷 Gate charge	$V_{GE} = -15 / 15\text{ V}, V_{CE} = 400\text{ V}$		Q_G		0,84		μC
内部栅极电阻 Internal gate resistor	$T_{vj} = 25^{\circ}\text{C}$		$R_{G\text{int}}$		0,0		Ω
输入电容 Input capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{ies}		14,3		nF
反向传输电容 Reverse transfer capacitance	$f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$		C_{res}		0,05		nF
集电极-发射极截止电流 Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	I_{CES}			1,0	mA
栅极-发射极漏电流 Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$		I_{GES}			100	nA
开通延迟时间(电感负载) Turn-on delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$		0,0269 0,0272 0,0276		μs μs μs
上升时间(电感负载) Rise time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_r		0,0114 0,0182 0,0194		μs μs μs
关断延迟时间(电感负载) Turn-off delay time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$		0,63 0,67 0,70		μs μs μs
下降时间(电感负载) Fall time, inductive load	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	t_f		0,03 0,032 0,034		μs μs μs
开通损耗能量(每脉冲) Turn-on energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 3500\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Gon} = 5,1\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{on}		0,72 0,93 0,94		mJ mJ mJ
关断损耗能量(每脉冲) Turn-off energy loss per pulse	$I_C = 100\text{ A}, V_{CE} = 300\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 3500\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Goff} = 39\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{off}		1,16 1,55 1,74		mJ mJ mJ
短路数据 SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{SCE} \cdot di/dt$	$t_p \leq 0\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	I_{SC}		1600		A
结 - 散热器热阻 Thermal resistance, junction to heatsink	每个 IGBT / per IGBT		$R_{th\text{ JH}}$			0,655	K/W
在开关状态下温度 Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

二极管, D1 / D4 / Diode, D1 / D4

最大额定值 / Maximum Rated Values

反向重复峰值电压 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
正向电流 Implemented forward current		I_{FN}	150	A
连续正向直流电流 Continuous DC forward current		I_F	100	A
正向重复峰值电流 Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	300	A
I ² t-值 I ² t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I ² t	760 680	A ² s A ² s

特征值 / Characteristic Values

				min.	typ.	max.	
正向电压 Forward voltage	$I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F		1,35 1,29 1,25	1,90	V V V
反向恢复峰值电流 Peak reverse recovery current	$I_F = 100\text{ A}, -di_F/dt = 3500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}		95,0 119 127		A A A
恢复电荷 Recovered charge	$I_F = 100\text{ A}, -di_F/dt = 3500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r		4,20 7,30 8,30		μC μC μC
反向恢复损耗 (每脉冲) Reverse recovery energy	$I_F = 100\text{ A}, -di_F/dt = 3500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}		0,71 1,34 1,54		mJ mJ mJ
结 - 散热器热阻 Thermal resistance, junction to heatsink	每个二极管 / per diode		R_{thJH}			0,976	K/W
在开关状态下温度 Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

二极管, D2 / D3 / Diode, D2 / D3

最大额定值 / Maximum Rated Values

反向重复峰值电压 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
正向电流 Implemented forward current		I_{FN}	150	A
连续正向直流电流 Continuous DC forward current		I_F	100	A
正向重复峰值电流 Repetitive peak forward current	$t_P = 1\text{ ms}$	I_{FRM}	300	A
I ² t-值 I ² t - value	$V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I ² t	760 680	A ² s A ² s

特征值 / Characteristic Values

				min.	typ.	max.	
正向电压 Forward voltage	$I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 100\text{ A}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	V_F		1,35 1,29 1,25	1,90	V V V
反向恢复峰值电流 Peak reverse recovery current	$I_F = 100\text{ A}, -di_F/dt = 3500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	I_{RM}		95,0 119 127		A A A
恢复电荷 Recovered charge	$I_F = 100\text{ A}, -di_F/dt = 3500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	Q_r		4,20 7,30 8,30		μC μC μC
反向恢复损耗 (每脉冲) Reverse recovery energy	$I_F = 100\text{ A}, -di_F/dt = 3500\text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $V_R = 300\text{ V}$ $V_{GE} = -15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	E_{rec}		0,71 1,34 1,54		mJ mJ mJ
结 - 散热器热阻 Thermal resistance, junction to heatsink	每个二极管 / per diode		R_{thJH}			1,00	K/W
在开关状态下温度 Temperature under switching conditions			$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

二极管, D5-D6 / Diode, D5-D6

最大额定值 / Maximum Rated Values

反向重复峰值电压 Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	V_{RRM}	650	V
正向电流 Implemented forward current		I_{FN}	120	A
连续正向直流电流 Continuous DC forward current		I_F	100	A
正向重复峰值电流 Repetitive peak forward current	$t_p = 1 \text{ ms}$	I_{FRM}	240	A
I ² t-值 I ² t - value	$V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	I^2t	470	A ² s
			420	A ² s

特征值 / Characteristic Values

		min.	typ.	max.	
正向电压 Forward voltage	$I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$ $T_{vj} = 25^{\circ}\text{C}$		1,45	2,30	V
	$I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$ $T_{vj} = 125^{\circ}\text{C}$	V_F	1,60		V
	$I_F = 100 \text{ A}, V_{GE} = 0 \text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		1,65		V
反向恢复峰值电流 Peak reverse recovery current	$I_F = 100 \text{ A}, -di_F/dt = 5500 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$	I_{RM}	90,0		A
	$V_R = 300 \text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		120		A
	$V_{GE} = -15 \text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		128		A
恢复电荷 Recovered charge	$I_F = 100 \text{ A}, -di_F/dt = 5500 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$	Q_r	6,63		μC
	$V_R = 300 \text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		6,00		μC
	$V_{GE} = -15 \text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		6,65		μC
反向恢复损耗 (每脉冲) Reverse recovery energy	$I_F = 100 \text{ A}, -di_F/dt = 5500 \text{ A}/\mu\text{s} (T_{vj}=150^{\circ}\text{C})$ $T_{vj} = 25^{\circ}\text{C}$	E_{rec}	0,51		mJ
	$V_R = 300 \text{ V}$ $T_{vj} = 125^{\circ}\text{C}$		0,94		mJ
	$V_{GE} = -15 \text{ V}$ $T_{vj} = 150^{\circ}\text{C}$		1,15		mJ
结 - 散热器热阻 Thermal resistance, junction to heatsink	每个二极管 / per diode	R_{thJH}		1,31	K/W
在开关状态下温度 Temperature under switching conditions		$T_{vj op}$	-40	150	$^{\circ}\text{C}$

负温度系数热敏电阻 / NTC-Thermistor

特征值 / Characteristic Values

		min.	typ.	max.	
额定电阻值 Rated resistance	$T_{NTC} = 25^{\circ}\text{C}$	R_{25}	5,00		k Ω
R100 偏差 Deviation of R100	$T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493 \Omega$	$\Delta R/R$	-5	5	%
耗散功率 Power dissipation	$T_{NTC} = 25^{\circ}\text{C}$	P_{25}		20,0	mW
B-值 B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/50}$	3375		K
B-值 B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/80}$	3411		K
B-值 B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/100}$	3433		K

根据应用手册标定

Specification according to the valid application note.

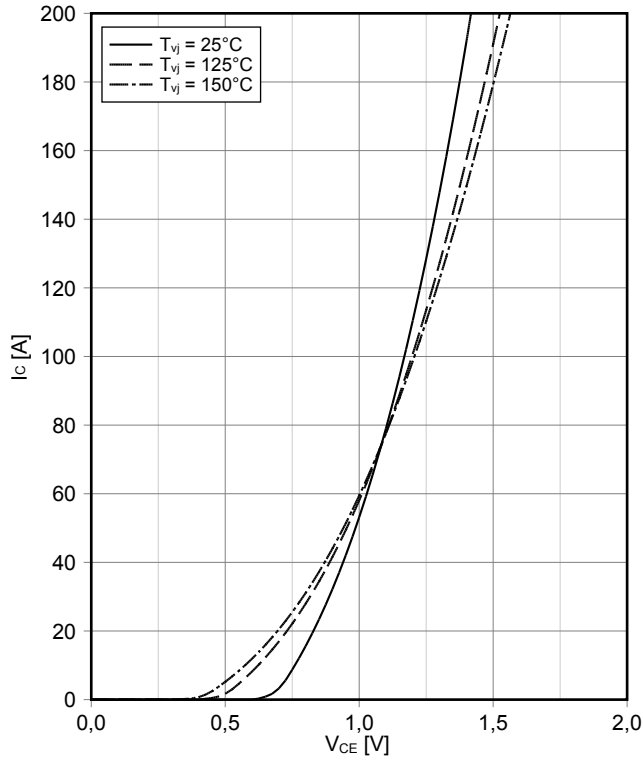
模块 / Module

绝缘测试电压 Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	V _{ISOL}	2,5		kV
内部绝缘 Internal isolation	基本绝缘 (class 1, IEC 61140) basic insulation (class 1, IEC 61140)		Al ₂ O ₃		
爬电距离 Creepage distance	端子至散热器 / terminal to heatsink 端子至端子 / terminal to terminal		11,5 6,3		mm
电气间隙 Clearance	端子至散热器 / terminal to heatsink 端子至端子 / terminal to terminal		10,0 5,0		mm
相对电痕指数 Comperative tracking index		CTI	> 200		
相对温度指数 (电) RTI Elec.	住房 housing	RTI	140		°C
			min.	typ.	max.
杂散电感, 模块 Stray inductance module		L _{sCE}		20	nH
储存温度 Storage temperature		T _{stg}	-40		125 °C
最高基板工作温度 Maximum baseplate operation temperature		T _{BPmax}			125 °C
Anpresskraft für mech. Bef. pro Feder mounting force per clamp		F	40	-	80 N
重量 Weight		G		39	g

Der Strom im Dauerbetrieb ist auf 25A effektiv pro Anschlusspin begrenzt.
 The current under continuous operation is limited to 25A rms per connector pin.
 Lagerung und Transport von Modulen mit TIM => siehe AN2012-07
 Storage and Shipment of modules with TIM => see AN2012-07

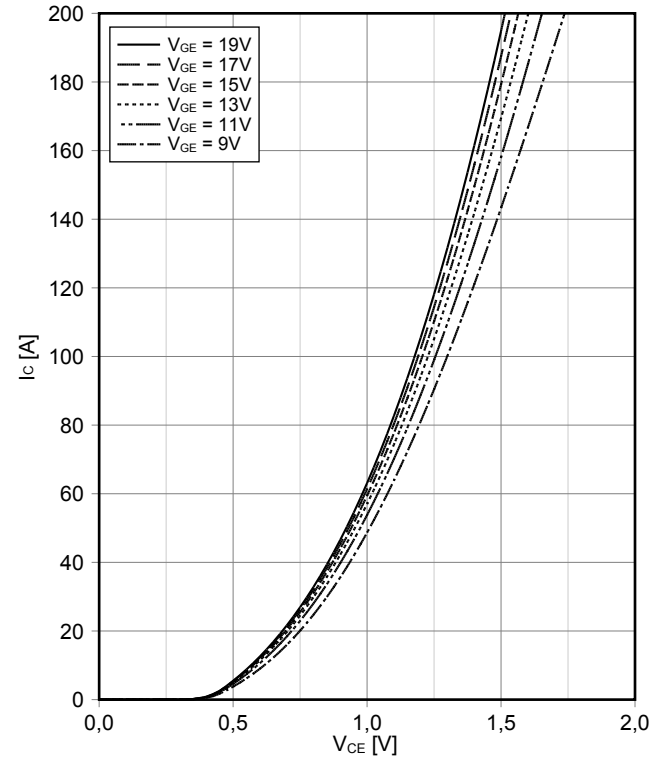
输出特性 IGBT, T1 / T4 (典型)
output characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



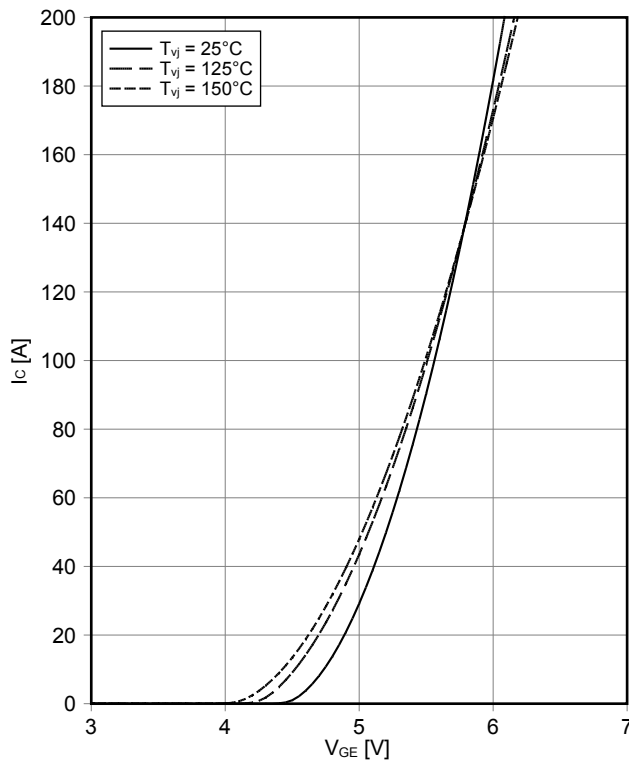
输出特性 IGBT, T1 / T4 (典型)
output characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



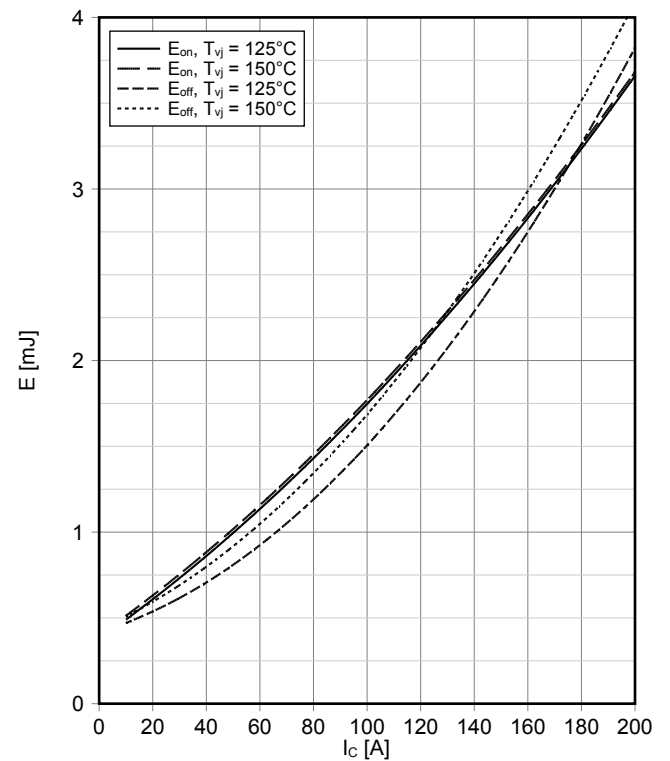
传输特性 IGBT, T1 / T4 (典型)
transfer characteristic IGBT, T1 / T4 (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$

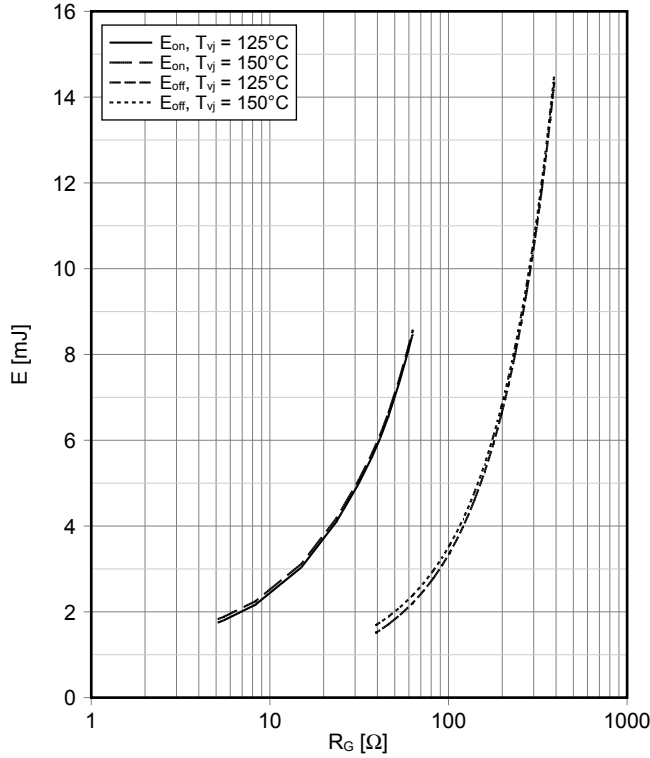


开关损耗 IGBT, T1 / T4 (典型)
switching losses IGBT, T1 / T4 (typical)

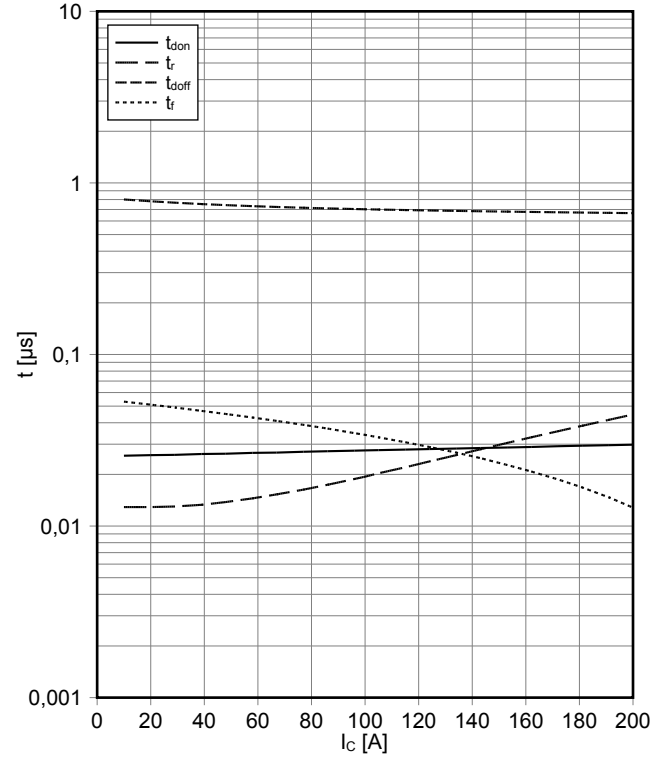
$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 5,1\ \Omega$, $R_{Goff} = 39\ \Omega$, $V_{CE} = 300\text{ V}$



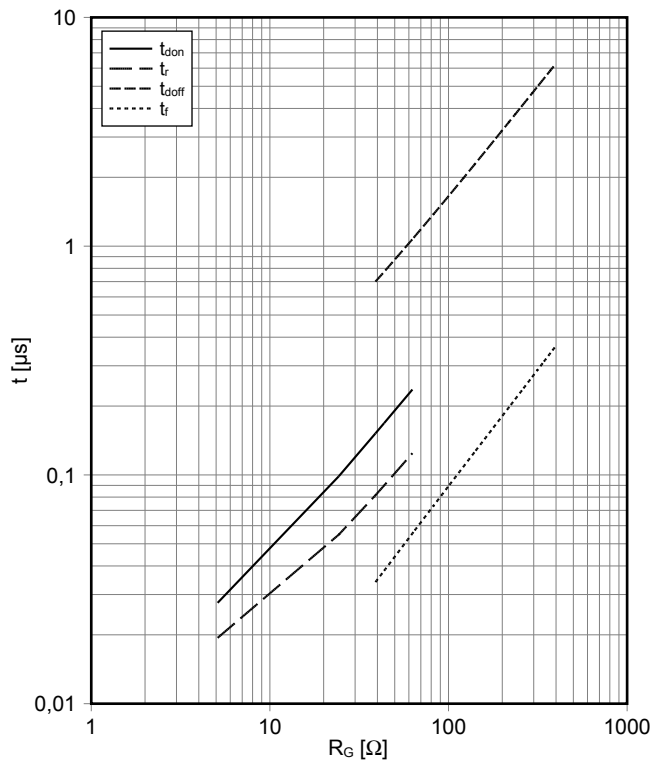
开关损耗 IGBT, T1 / T4 (典型)
switching losses IGBT, T1 / T4 (typical)
 $E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 100\text{ A}, V_{CE} = 300\text{ V}$



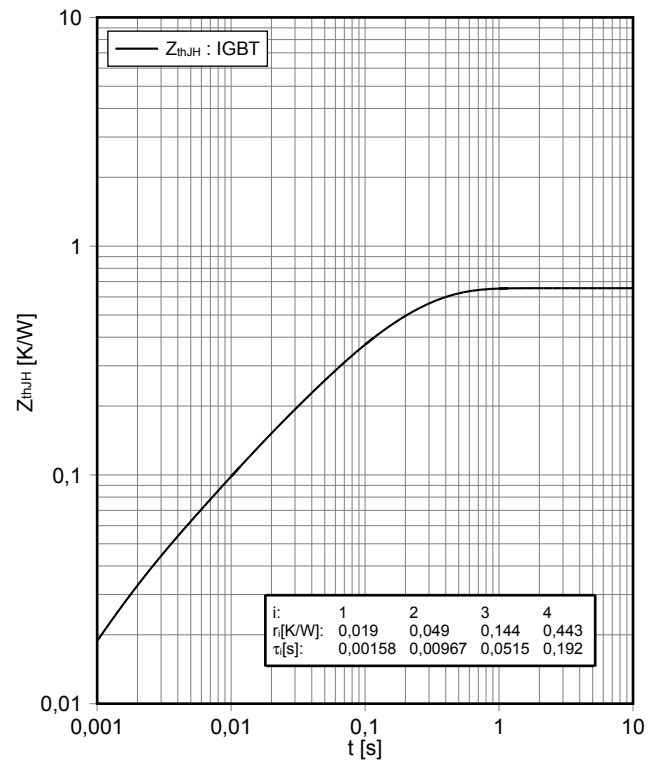
??? IGBT, T1 / T4 (典型)
switching times IGBT, T1 / T4 (typical)
 $t_{don} = f(I_C), t_r = f(I_C), t_{doff} = f(I_C), t_f = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 5.1\ \Omega, R_{Goff} = 39\ \Omega, V_{CE} = 300\text{ V}, T_{vj} = 150\ \text{°C}$



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switching times IGBT, T1 / T4 (typical)
 $t_{don} = f(R_G), t_r = f(R_G), t_{doff} = f(R_G), t_f = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 5.1\ \Omega, R_{Goff} = 39\ \Omega, V_{CE} = 300\text{ V}, T_{vj} = 150\ \text{°C}$

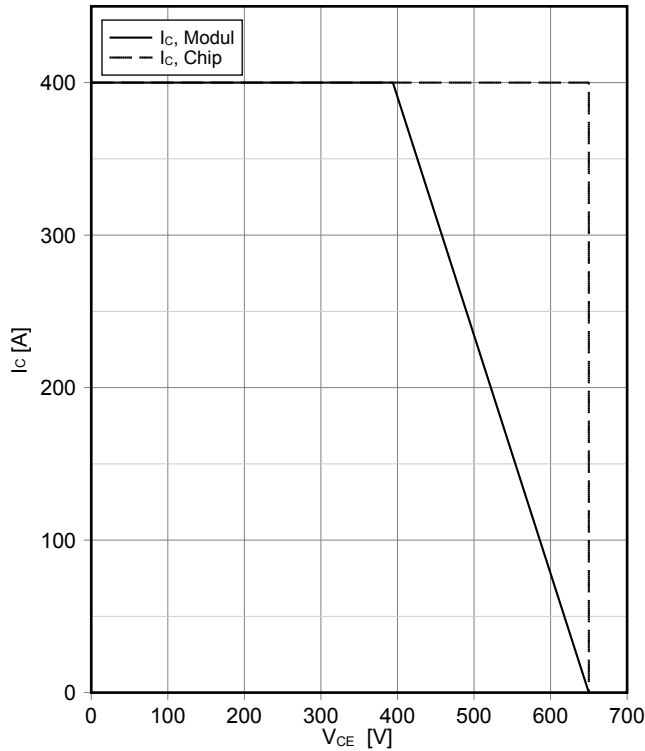


瞬态热阻抗 IGBT, T1 / T4
transient thermal impedance IGBT, T1 / T4
 $Z_{thJH} = f(t)$



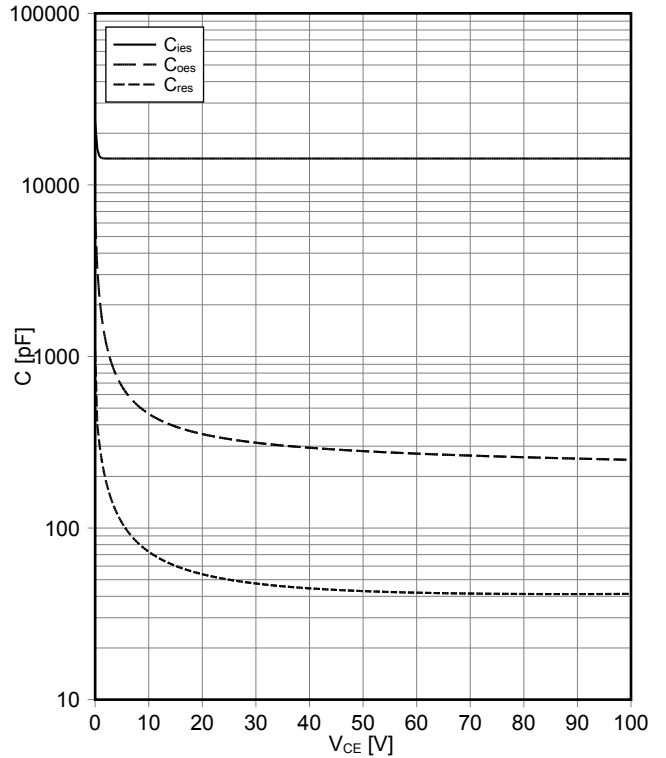
反偏安全工作区 IGBT, T1 / T4 (RBSOA)
reverse bias safe operating area IGBT, T1 / T4 (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 39 \Omega$, $T_{vj} = 150^\circ\text{C}$



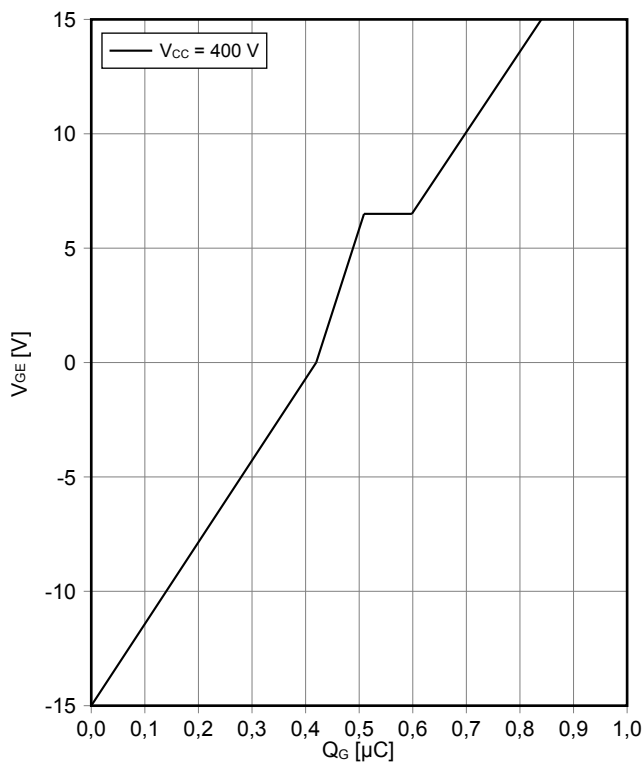
电容特性 IGBT, T1 / T4 (典型)
capacity characteristic IGBT, T1 / T4 (typical)

$C = f(V_{CE})$
 $V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$



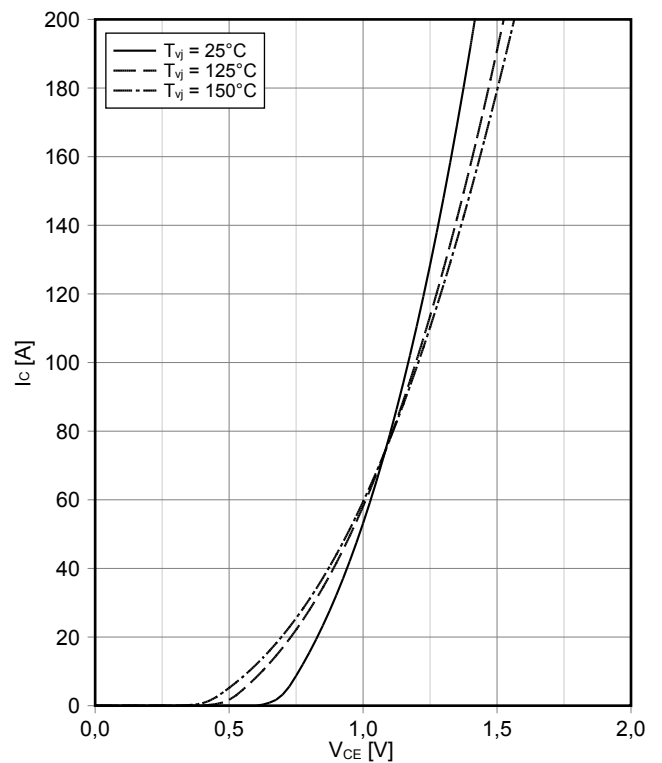
栅极电荷特性 IGBT, T1 / T4 (典型)
gate charge characteristic IGBT, T1 / T4 (typical)

$V_{GE} = f(Q_G)$
 $I_C = 100 \text{ A}$, $T_{vj} = 25^\circ\text{C}$



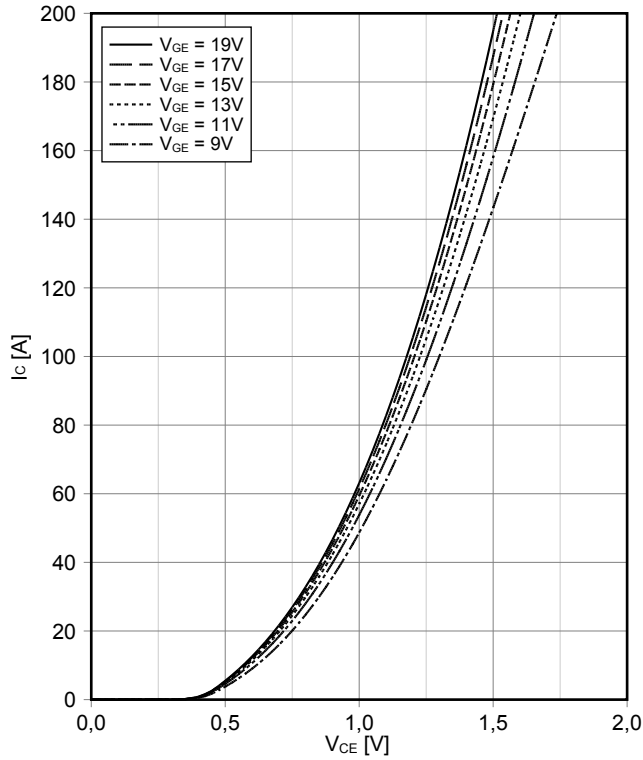
输出特性 IGBT, T2 / T3 (典型)
output characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15 \text{ V}$



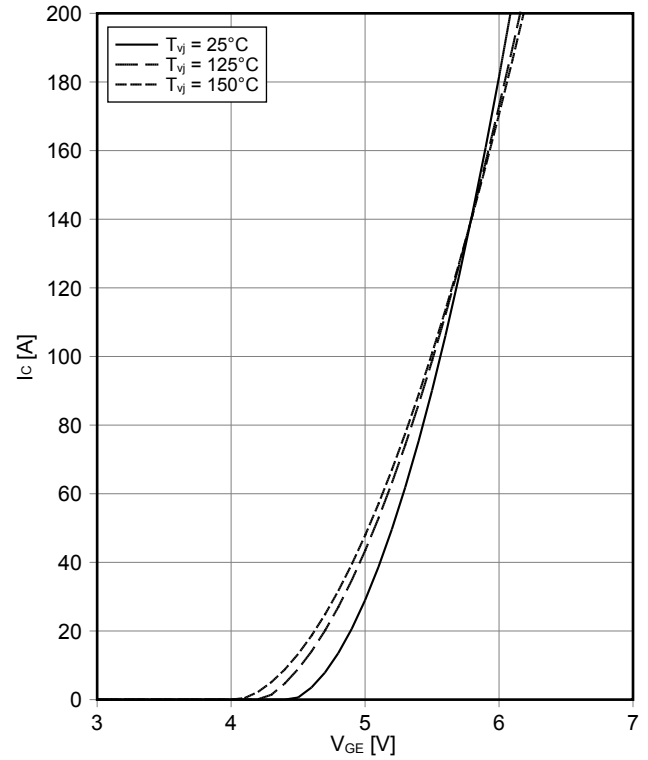
输出特性 IGBT, T2 / T3 (典型)
output characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 150^\circ\text{C}$



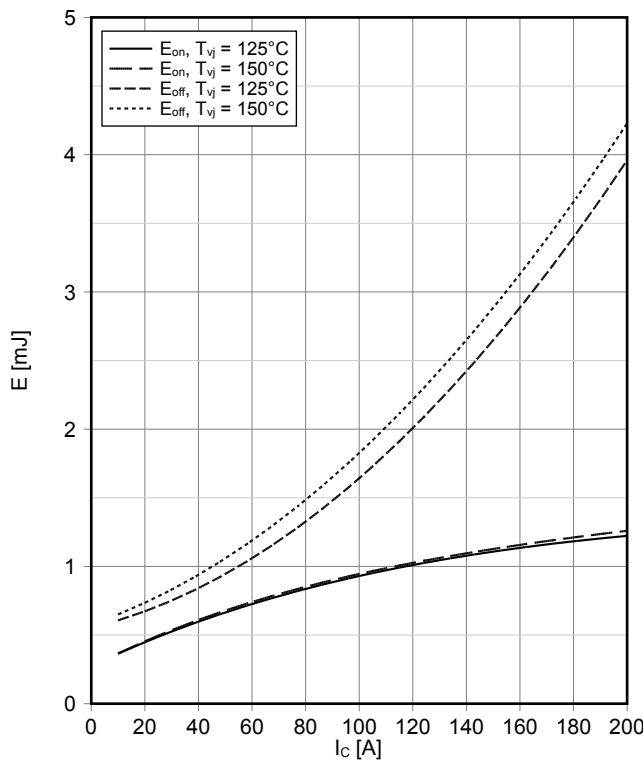
传输特性 IGBT, T2 / T3 (典型)
transfer characteristic IGBT, T2 / T3 (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



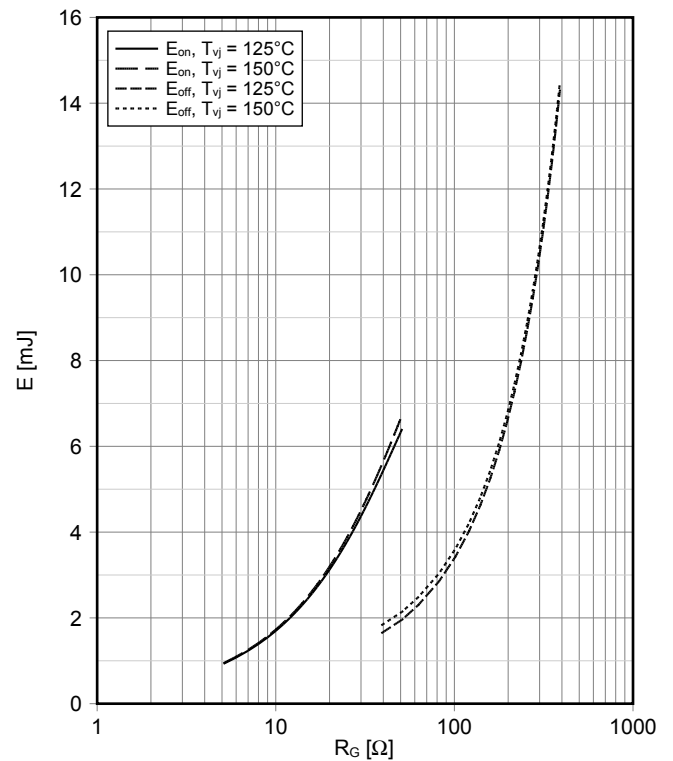
开关损耗 IGBT, T2 / T3 (典型)
switching losses IGBT, T2 / T3 (typical)

$E_{on} = f(I_C), E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 5.1\ \Omega, R_{Goff} = 39\ \Omega, V_{CE} = 300\text{ V}$



开关损耗 IGBT, T2 / T3 (典型)
switching losses IGBT, T2 / T3 (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 100\text{ A}, V_{CE} = 300\text{ V}$

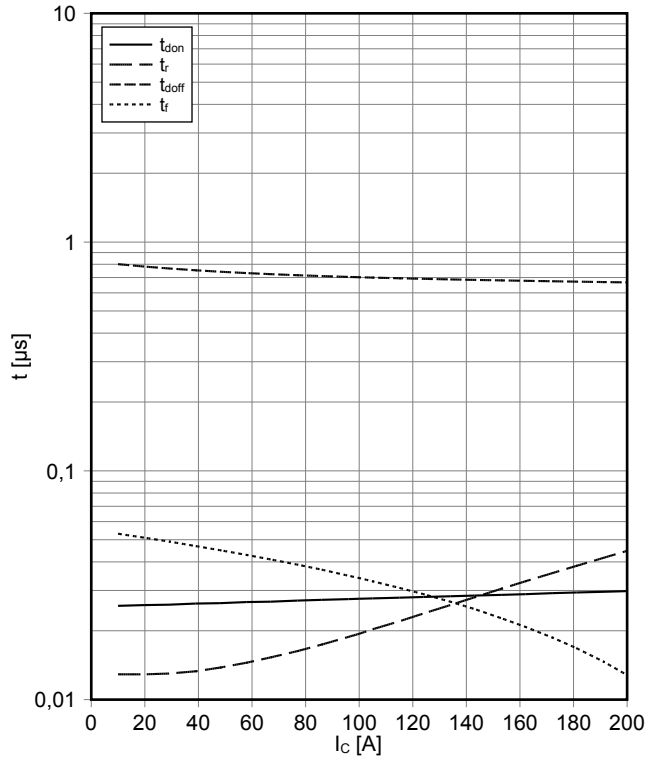


??? IGBT, T2 / T3 (典型)

switching times IGBT, T2 / T3 (typical)

$t_{don} = f(I_C)$, $t_r = f(I_C)$, $t_{doff} = f(I_C)$, $t_f = f(I_C)$

$V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 5.1\ \Omega$, $R_{Goff} = 39\ \Omega$, $V_{CE} = 300\text{ V}$, $T_{vj} = 150\text{ }^\circ\text{C}$

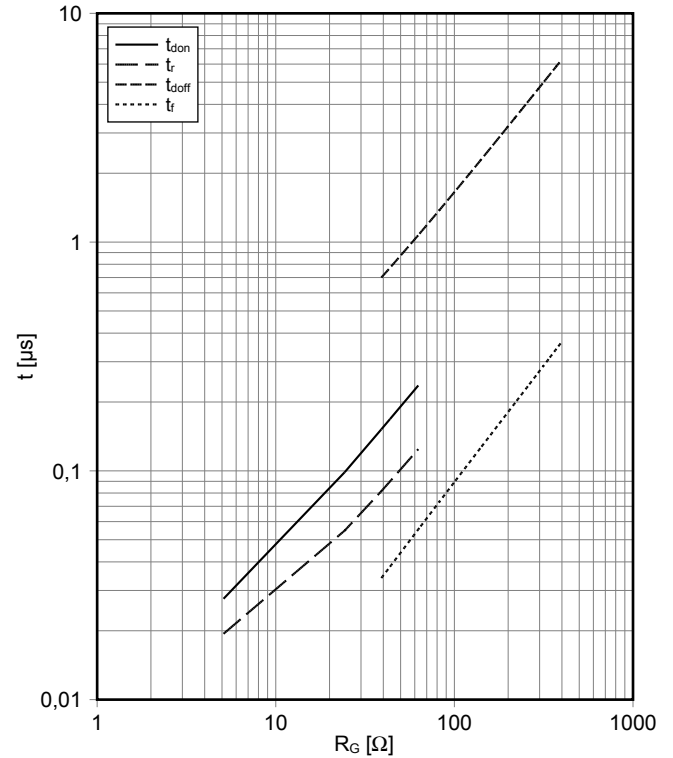


??? IGBT, T2 / T3 (典型)

switching times IGBT, T2 / T3 (typical)

$t_{don} = f(R_G)$, $t_r = f(R_G)$, $t_{doff} = f(R_G)$, $t_f = f(R_G)$

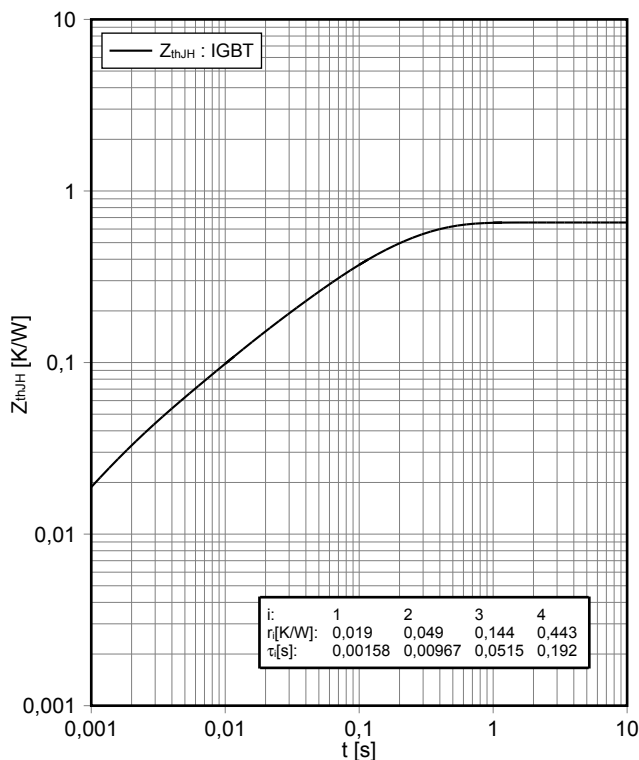
$V_{GE} = \pm 15\text{ V}$, $I_C = 100\text{ A}$, $V_{CE} = 300\text{ V}$, $T_{vj} = 150\text{ }^\circ\text{C}$



瞬态热阻抗 IGBT, T2 / T3

transient thermal impedance IGBT, T2 / T3

$Z_{thJH} = f(t)$

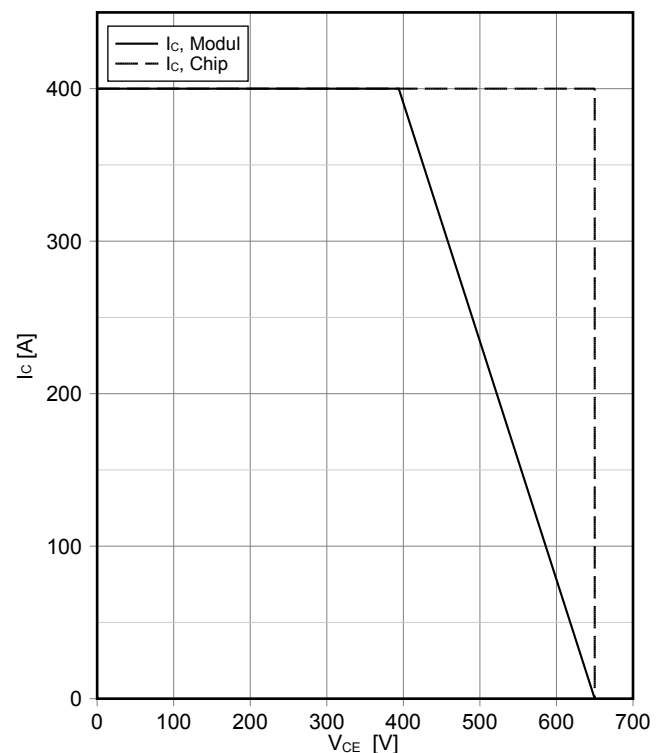


反偏安全工作区 IGBT, T2 / T3 (RBSOA)

reverse bias safe operating area IGBT, T2 / T3 (RBSOA)

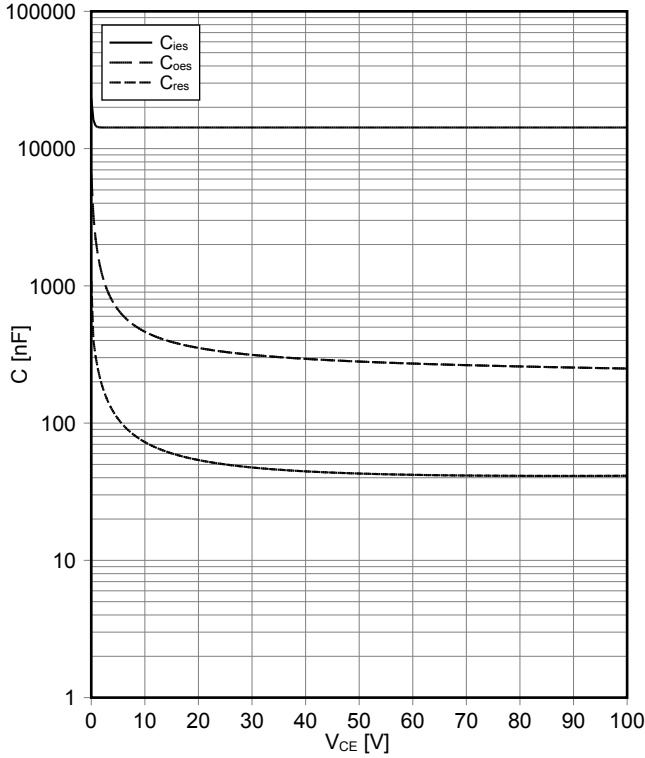
$I_C = f(V_{CE})$

$V_{GE} = \pm 15\text{ V}$, $R_{Goff} = 39\ \Omega$, $T_{vj} = 150\text{ }^\circ\text{C}$



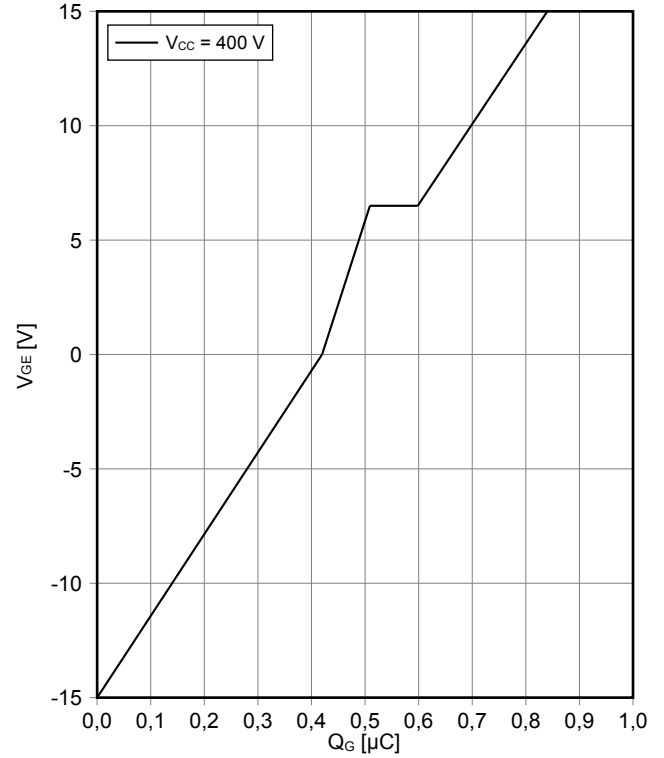
电容特性 IGBT, T2 / T3 (典型)
capacity characteristic IGBT, T2 / T3 (typical)

$C = f(V_{CE})$
 $V_{GE} = 0 \text{ V}, T_{vj} = 25^\circ\text{C}, f = 100\text{kHz}$



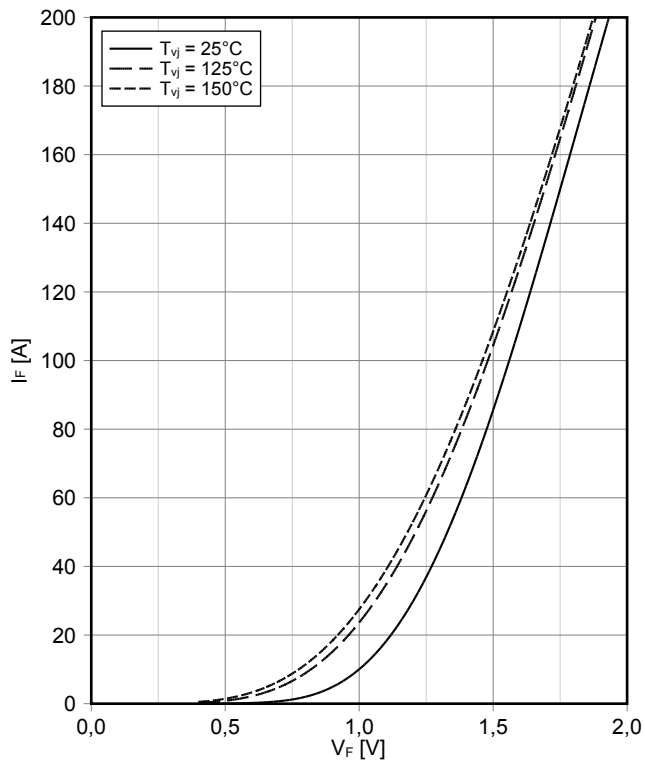
栅极电荷特性 IGBT, T2 / T3 (典型)
gate charge characteristic IGBT, T2 / T3 (typical)

$V_{GE} = f(Q_G)$
 $I_C = 100 \text{ A}, T_{vj} = 25^\circ\text{C}$



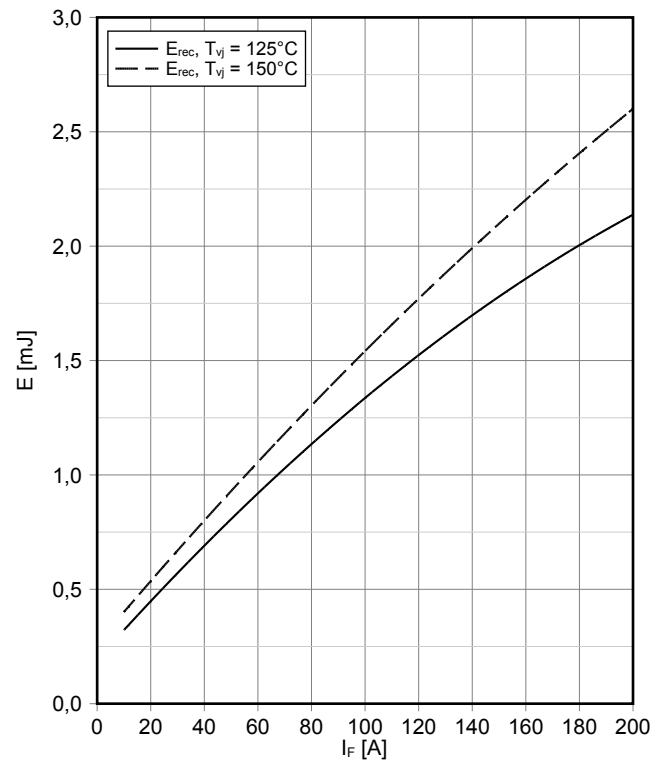
正向偏压特性 二极管, D1 / D4 (典型)
forward characteristic of Diode, D1 / D4 (typical)

$I_F = f(V_F)$



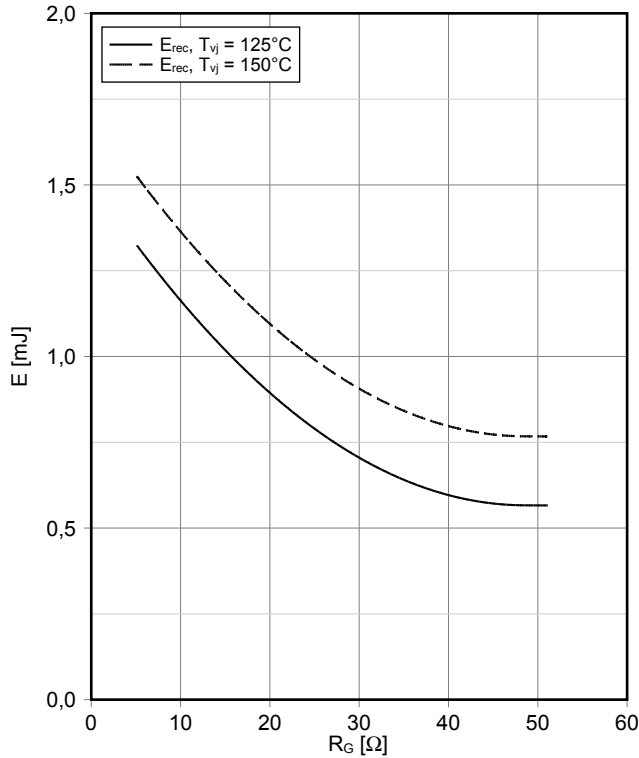
开关损耗 二极管, D1 / D4 (典型)
switching losses Diode, D1 / D4 (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 5.1 \Omega, V_{CE} = 300 \text{ V}$



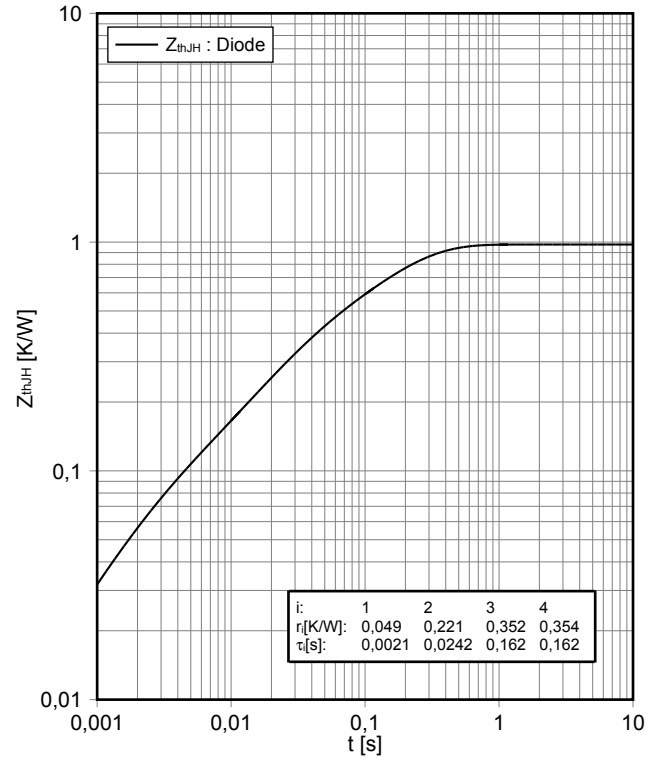
开关损耗 二极管, D1 / D4 (典型)
switching losses Diode, D1 / D4 (typical)

$E_{rec} = f(R_G)$
 $I_F = 100\text{ A}, V_{CE} = 300\text{ V}$



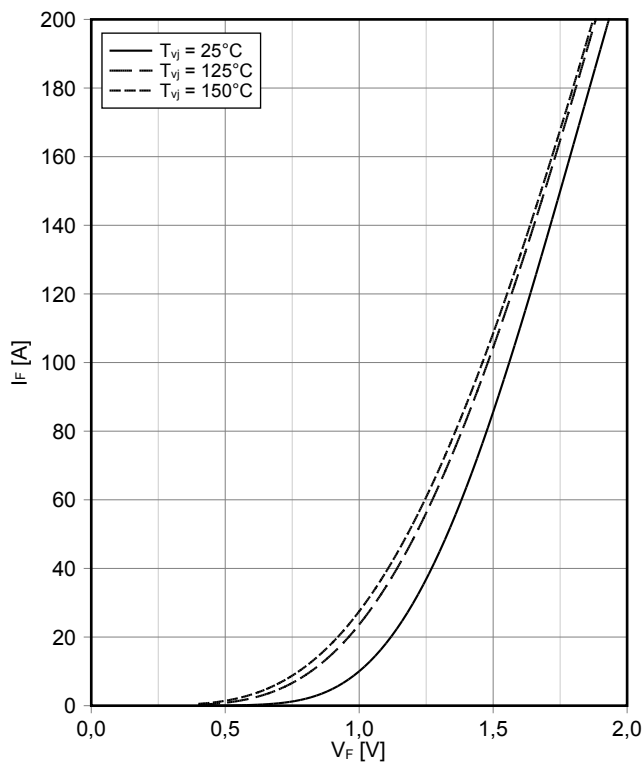
瞬态热阻抗 二极管, D1 / D4
transient thermal impedance Diode, D1 / D4

$Z_{thJH} = f(t)$



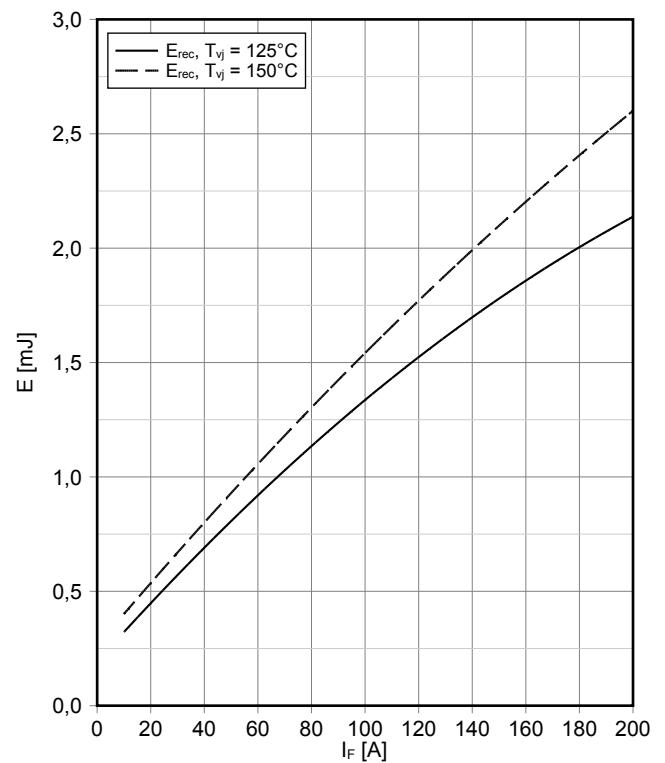
正向偏压特性 二极管, D2 / D3 (典型)
forward characteristic of Diode, D2 / D3 (typical)

$I_F = f(V_F)$



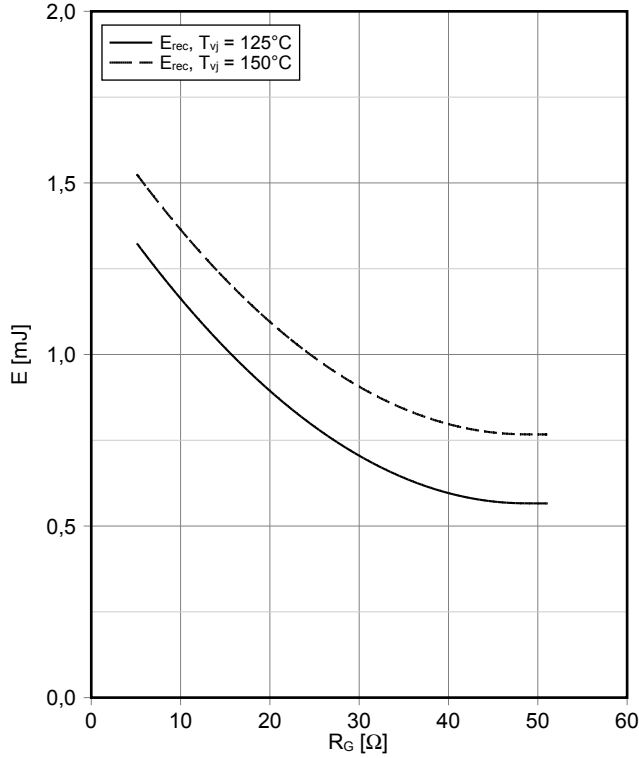
开关损耗 二极管, D2 / D3 (典型)
switching losses Diode, D2 / D3 (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 5,1\ \Omega, V_{CE} = 300\text{ V}$



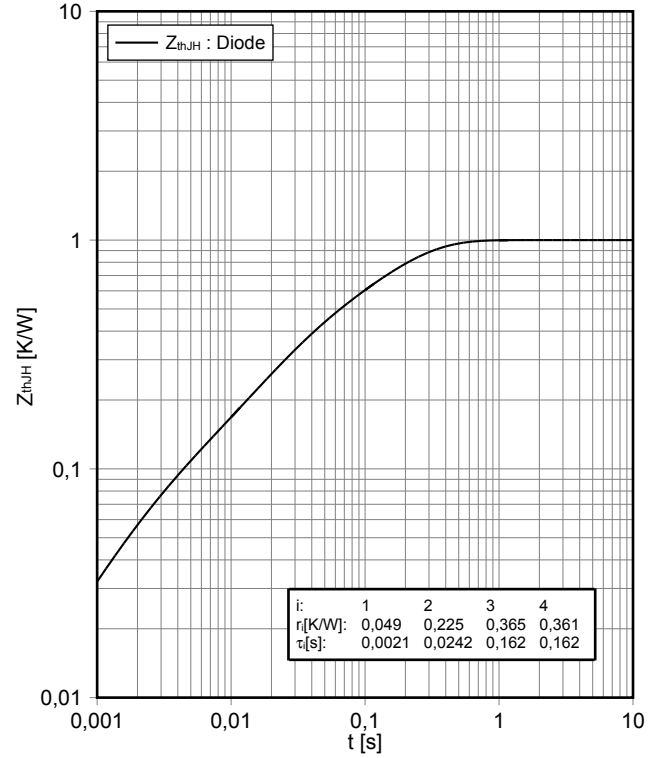
开关损耗 二极管, D2 / D3 (典型)
switching losses Diode, D2 / D3 (typical)

$E_{rec} = f(R_G)$
 $I_F = 100\text{ A}, V_{CE} = 300\text{ V}$



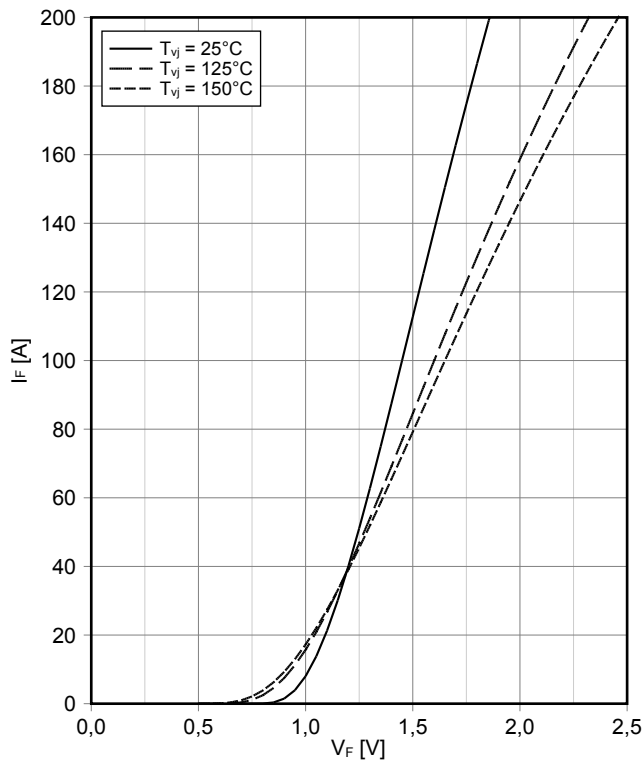
瞬态热阻抗 二极管, D2 / D3
transient thermal impedance Diode, D2 / D3

$Z_{thJH} = f(t)$



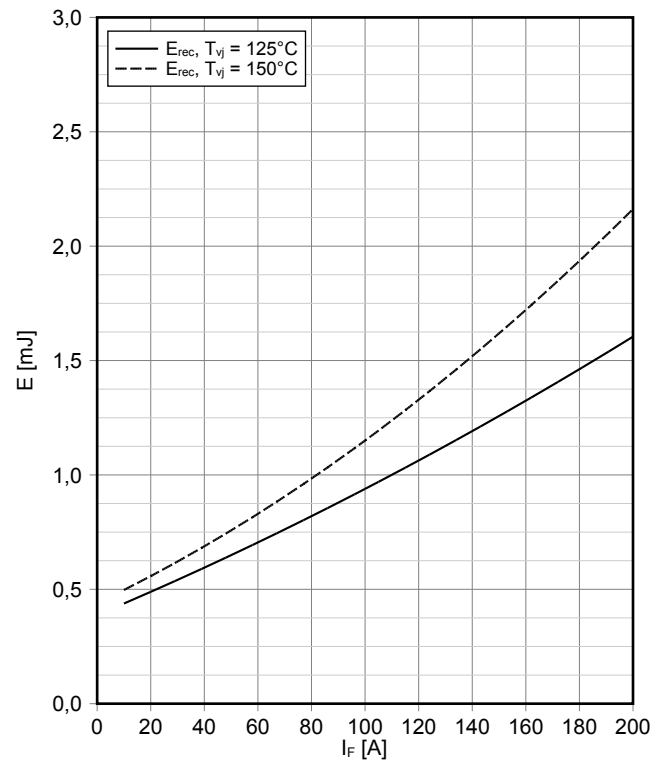
正向偏压特性 二极管, D5-D6 (典型)
forward characteristic of Diode, D5-D6 (typical)

$I_F = f(V_F)$



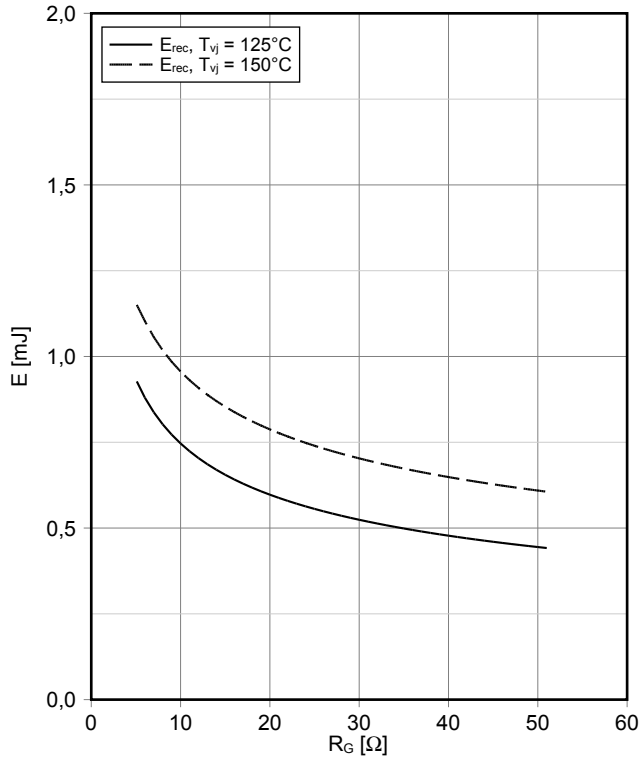
开关损耗 二极管, D5-D6 (典型)
switching losses Diode, D5-D6 (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 5,1\ \Omega, V_{CE} = 300\text{ V}$



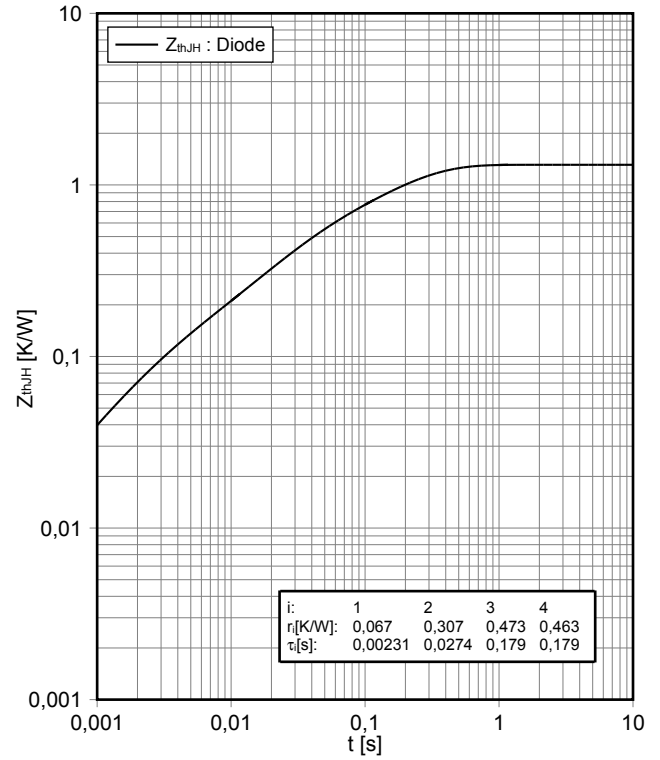
开关损耗 二极管, D5-D6 (典型)
switching losses Diode, D5-D6 (typical)

$E_{rec} = f(R_G)$
 $I_F = 100\text{ A}, V_{CE} = 300\text{ V}$



瞬态热阻抗 二极管, D5-D6
transient thermal impedance Diode, D5-D6

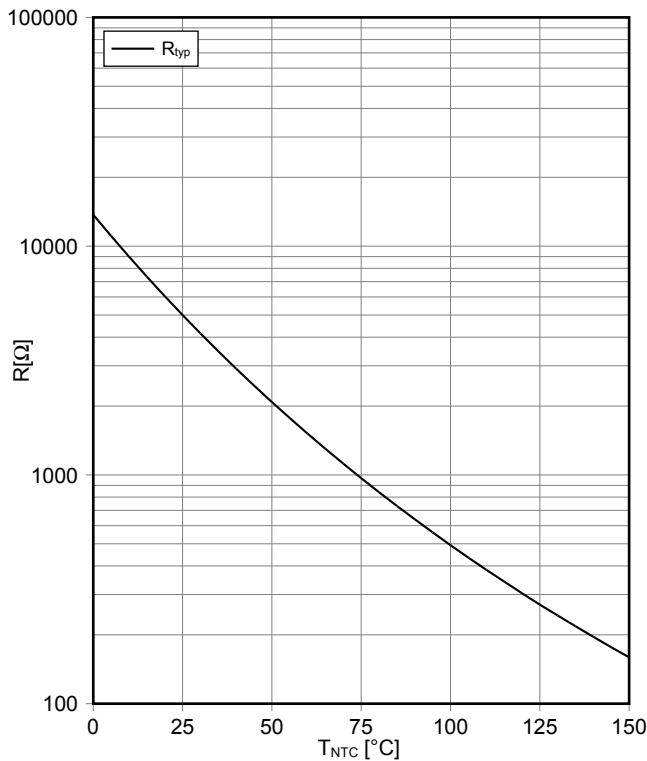
$Z_{thJH} = f(t)$



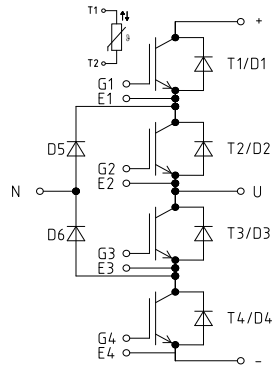
i:	1	2	3	4
r[K/W]:	0,067	0,307	0,473	0,463
τ[s]:	0,00231	0,0274	0,179	0,179

负温度系数热敏电阻 温度特性
NTC-Thermistor-temperature characteristic (typical)

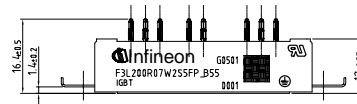
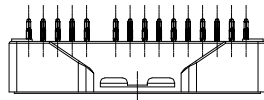
$R = f(T_{NTC})$



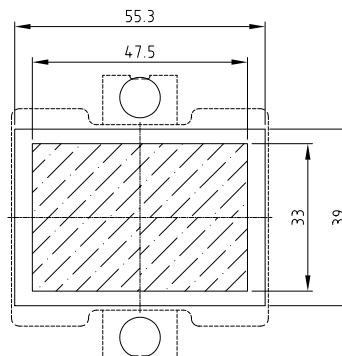
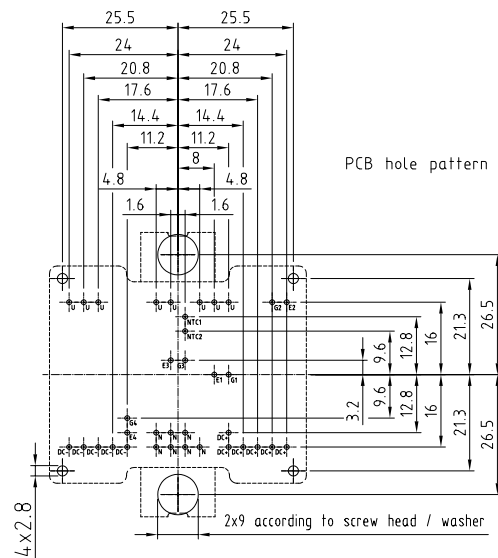
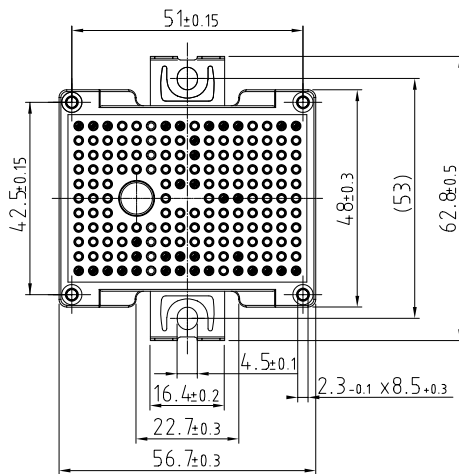
接线图 / Circuit diagram



封装尺寸 / Package outlines



- Pin-Grid 3.2mm
- Tolerance of PCB hole pattern $\varnothing 0.1$
- Hole specification for contacts see AN 2009-01:
Diameters of drill $\varnothing 1.15\text{mm}$
and copper thickness in hole 25-50 μm



restricted area for Thermal Interface Material

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Edition 2020-03-06

Published by
Infineon Technologies AG
81726 München, Germany

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Email: erratum@infineon.com

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